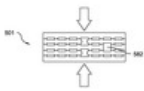
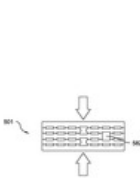
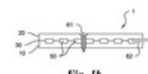
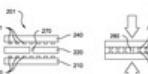
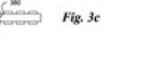
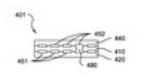
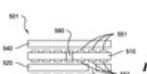
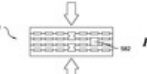
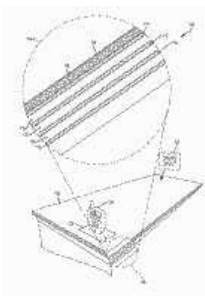
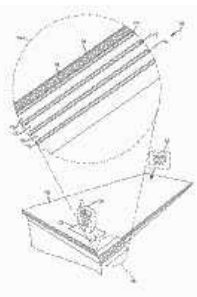
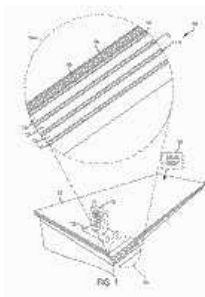
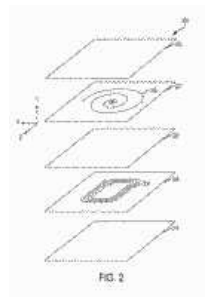
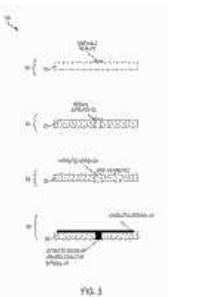
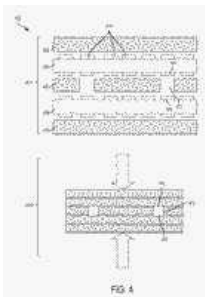
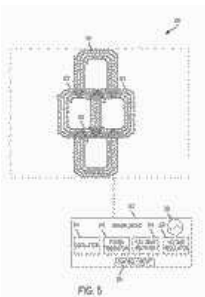
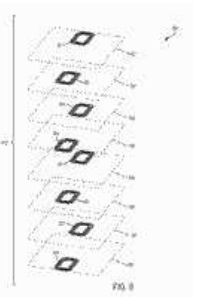
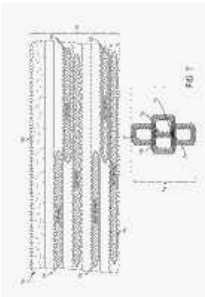
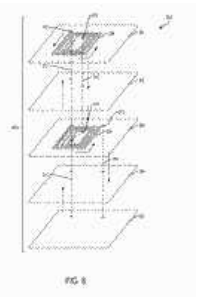
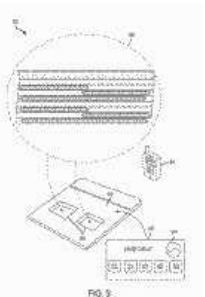
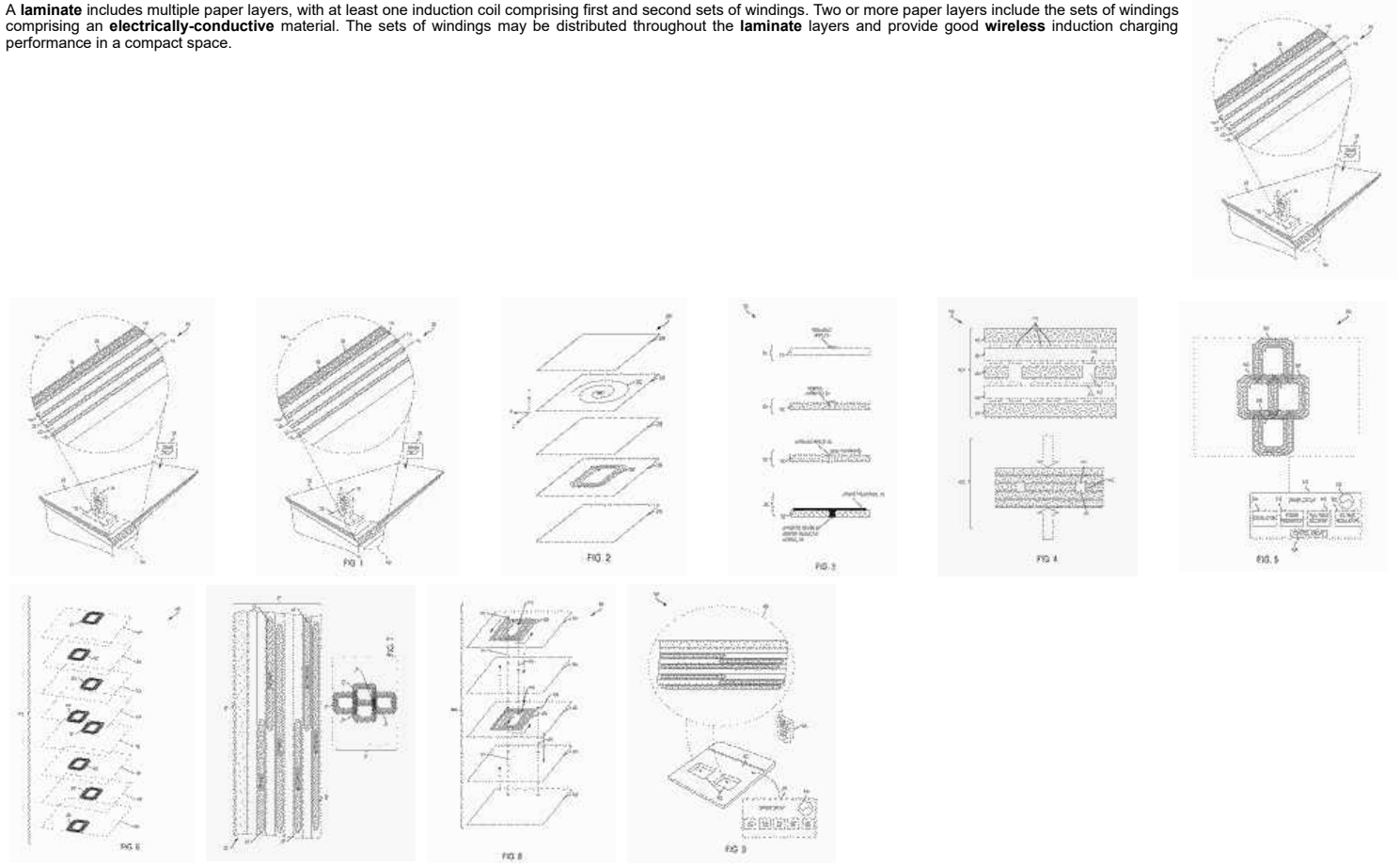


34 results for 29 AND LAMINATE AND ELECTRIC+ AND WIRELESS AND (DECORAT+ OR PATTERN) - Collection: FAMPAT

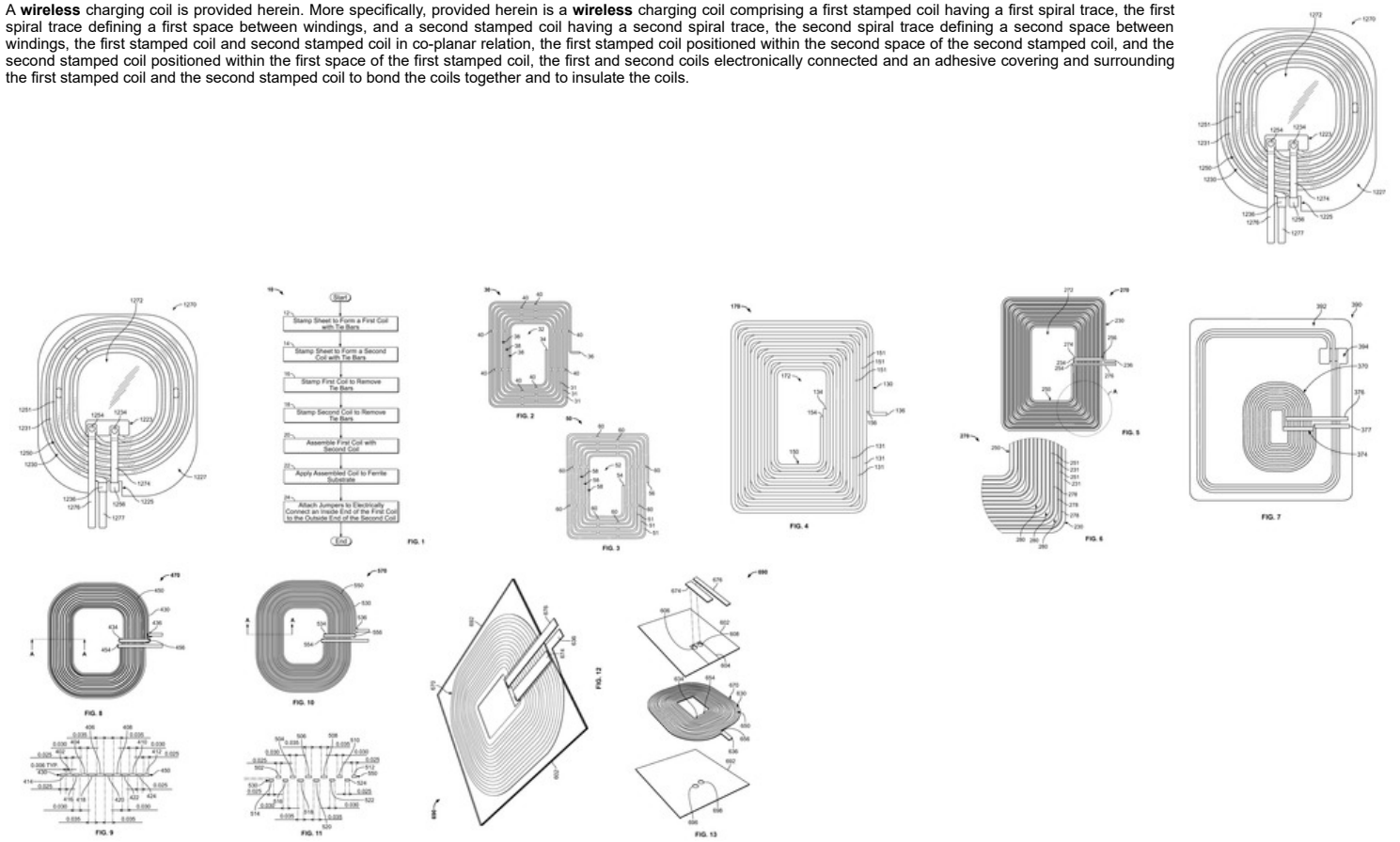
#	 	Title	Publication number	1st app. date	Applicant/Assignee	1st publ. date	Publ. date	
1.		Decorative multi-layer surfacing materials having embedded conductive materials, solid surfaces made therewith, methods for making such surfacing materials and uses therefor	CA2963975	2015-10-13	DELI MUSIC DILLER* FORMICA	2016-04-14	2016-04-14	
Decorative, multi-layer surfacing materials, surfaces made therewith, methods of making such and wireless power transmission using the same, which surfacing materials comprise: a first resin-impregnated paper layer and a second resin-impregnated paper layer, and a first conductive material having a first terminus and a second terminus and capable of carrying an electric current from the first terminus to the second terminus; wherein the first conductive material is disposed on a first surface of the first resin-impregnated paper layer; wherein the first resin- impregnated paper layer and the second resin-impregnated paper layer are disposed in a stacked and compressed such that the first conductive material is encapsulated between the first resin- impregnated paper layer and the second resin-impregnated paper layer; and wherein at least one of the first resin-impregnated paper layer, the second resin-impregnated paper layer or an optional additional resin-impregnated paper layer is a decorative layer.								
         								

2.		Laminate with induction coils and charging station device comprising same	US20180301268	2017-04-14	DILLER*	2018-10-18	2018-10-18	
A laminate includes multiple paper layers, with at least one induction coil comprising first and second sets of windings. Two or more paper layers include the sets of windings comprising an electrically-conductive material. The sets of windings may be distributed throughout the laminate layers and provide good wireless induction charging performance in a compact space.								
         								

A **laminate** includes multiple paper layers, with at least one induction coil comprising first and second sets of windings. Two or more paper layers include the sets of windings comprising an **electrically-conductive** material. The sets of windings may be distributed throughout the **laminate** layers and provide good **wireless** induction charging performance in a compact space.



A **wireless** charging coil is provided herein. More specifically, provided herein is a **wireless** charging coil comprising a first stamped coil having a first spiral trace, the first spiral trace defining a first space between windings, and a second stamped coil having a second spiral trace, the second spiral trace defining a second space between windings, the first stamped coil and second stamped coil in co-planar relation, the first stamped coil positioned within the second space of the second stamped coil, and the second stamped coil positioned within the first space of the first stamped coil, the first and second coils electronically connected and an adhesive covering and surrounding the first stamped coil and the second stamped coil to bond the coils together and to insulate the coils.



5. Shield part, method of fabricating the same, and contactless power transmission device having the shield part

KR101474149

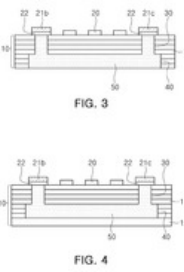
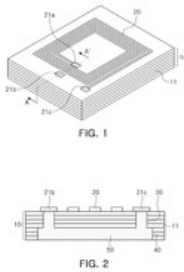
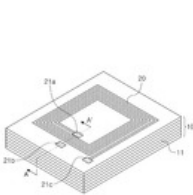
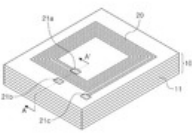
2013-06-28

SAMSUNG ELECTRO MECHANICS*

2014-12-17

2014-12-17

There is provided a shield part including: a magnetic **laminated** formed by laminating a plurality of magnetic layers and having a first surface and a second surface; a coil **pattern** formed on the first surface; and a first lead part formed at an end portion of a central portion of the coil **pattern** and a second lead part formed outside of the coil **pattern**, wherein a portion of the second surface is removed to form a recess, the first lead part is **electrically** connected to the second lead part by a conductive material disposed in the recess and a first via formed in the magnetic **laminated** in a lamination direction, and the second lead part is **electrically** connected to the first lead part by the conductive material disposed in the recess and a second via formed in the magnetic **laminated** in the lamination direction.



6. Antenna module

WO2014088028

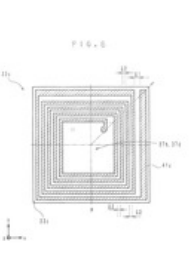
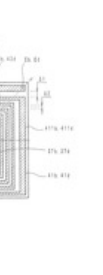
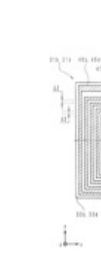
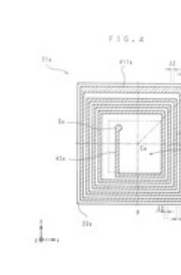
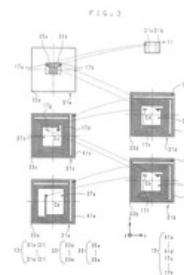
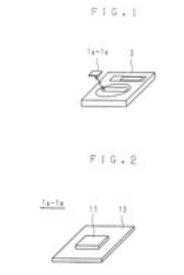
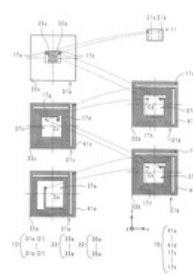
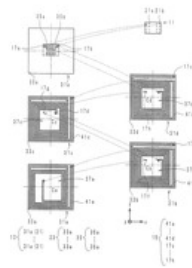
2013-12-04

MURATA MANUFACTURING*

2014-06-12

2014-06-12

To improve reliability, an antenna module is, for example, an RFID tag (1a), and one coil **pattern** (41) has a spiral shape wound three or more turns in approximately parallel to the outer edge of a principal surface. One via conductor (17) is joined to an outer periphery-side end (E) of the coil **pattern** (41), and another via conductor (17) is joined to an inner periphery-side end (S) of the coil **pattern** (41). The coil **pattern** (41) has a first partial **pattern** (45) including the outer periphery-side end (E) and parallel to one end of the principal surface, a second partial **pattern** (47) parallel to the first partial **pattern** (45) and adjacent to the first partial **pattern** (45) with a first line-to-line gap ($\Delta 1$) therebetween, and a third partial **pattern** (49) parallel to the second partial **pattern** (47) and adjacent to the second partial **pattern** (47) with a second line-to-line gap ($\Delta 2$) narrower than the first line-to-line gap ($\Delta 1$) therebetween.



7. Incombustible sound-absorbing electric radiation-absorbing ceiling panel

CN1279326

2000-05-29

NITTO BOSEKI*

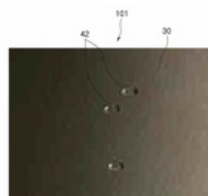
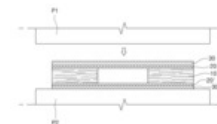
2001-01-10

2001-01-10

The present invention provides a ceiling panel intended for good design which exhibits a light weight, sufficient flexural strength, incombustibility, sound-absorbing properties and heat insulation properties and desirable **electric** radiation-absorbing properties as an interior ceiling panel that acts as a best member for solving problems with communications by **wireless** LAN. The present invention also provides an interior ceiling panel having enhanced **electric** radiation barrier properties attained by applying a metal foil to the foregoing ceiling panel. A novel incombustible sound-absorbing **electric** radiation-absorbing ceiling panel having a thickness of from 1 mm to 30 mm is obtained by subjecting a water-dispersed slurry of a mixture of from 67 to 92 wt-% of a rock wool, from 0.5 to 8 wt-% of a beaten pulp, from 2 to 13 wt-% of a binder made of an organic resin, from 0.15 to 1 wt-% of a flocculating agent, from 0.5 to 10 wt-% of a natural mineral fiber and from 0.02 to 1 wt-% of a carbon fiber having a fiber length of from 1 mm to 30 mm to wet paper making.

物理特性値 (単位: mm)						
項目	単位	200	300	400	500	600
密度 (g/cm ³)	g/cm ³	0.05	0.06	0.07	0.08	0.09
引張強度 (N/mm ²)	N/mm ²	0.1	0.2	0.3	0.4	0.5
圧縮強度 (N/mm ²)	N/mm ²	0.1	0.2	0.3	0.4	0.5
引張率 (%)	%	10	20	30	40	50
圧縮率 (%)	%	10	20	30	40	50
引張率 (%)	%	10	20	30	40	50
圧縮率 (%)	%	10	20	30	40	50

物理特性値 (単位: mm)						
項目	単位	200	300	400	500	600
密度 (g/cm ³)	g/cm ³	0.05	0.06	0.07	0.08	0.09
引張強度 (N/mm ²)	N/mm ²	0.1	0.2	0.3	0.4	0.5
圧縮強度 (N/mm ²)	N/mm ²	0.1	0.2	0.3	0.4	0.5
引張率 (%)	%	10	20	30	40	50
圧縮率 (%)	%	10	20	30	40	50
引張率 (%)	%	10	20	30	40	50
圧縮率 (%)	%	10	20	30	40	50

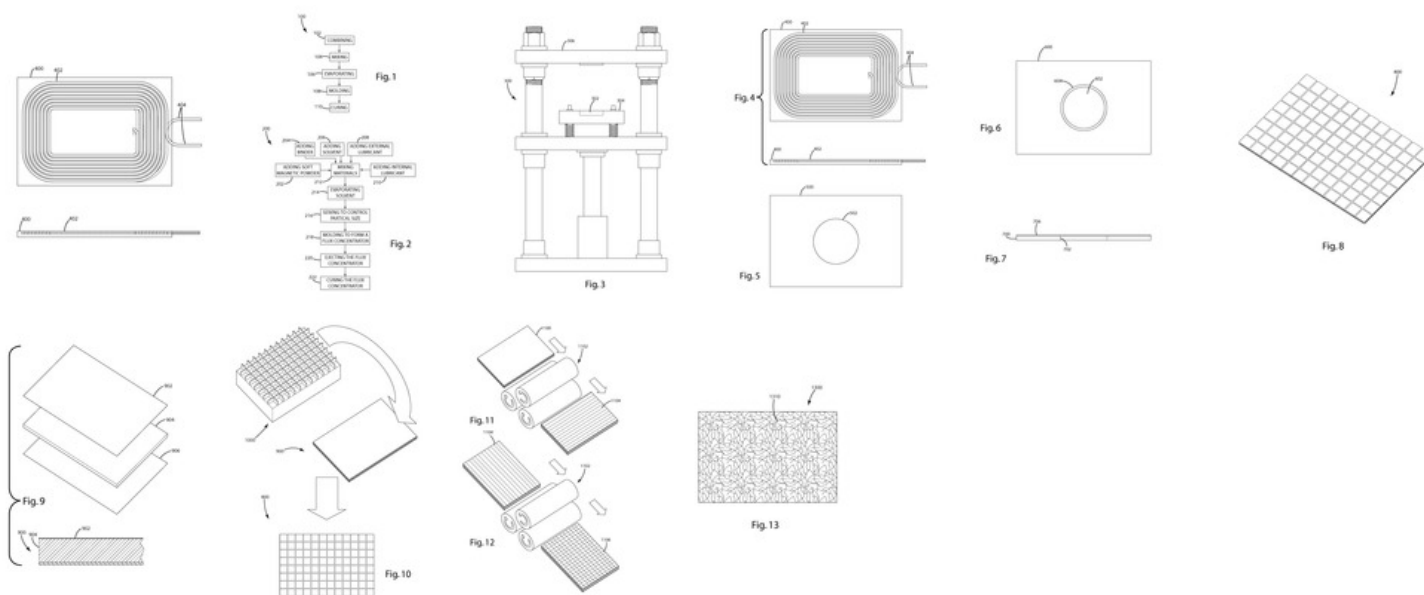
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2015-05-07 2015-05-07

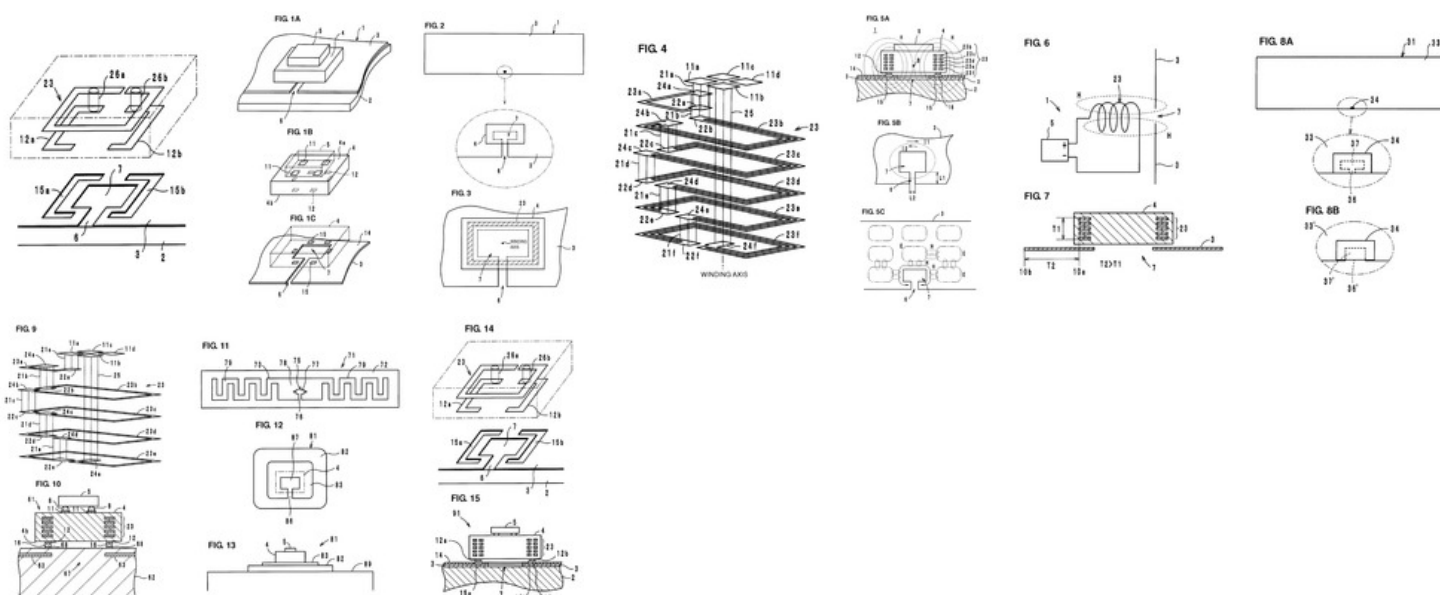
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新製品商品	0.19	0.34
2007-08に付与された「100%」の 了後の商品	0.34	0.32
新製品の売上	-0.03	-0.02
商品名(1)と単位(2)のコード名(3)	-0.02	

	右子集	右子集
数据集1与数据集2的Jaccard (J20)		
数据集1与数据集2的Jaccard	0.35	0.35
数据集1与数据集2的Jaccard	0.34	0.32
数据集1的Jaccard	-0.01	-0.01
数据集2的Jaccard		

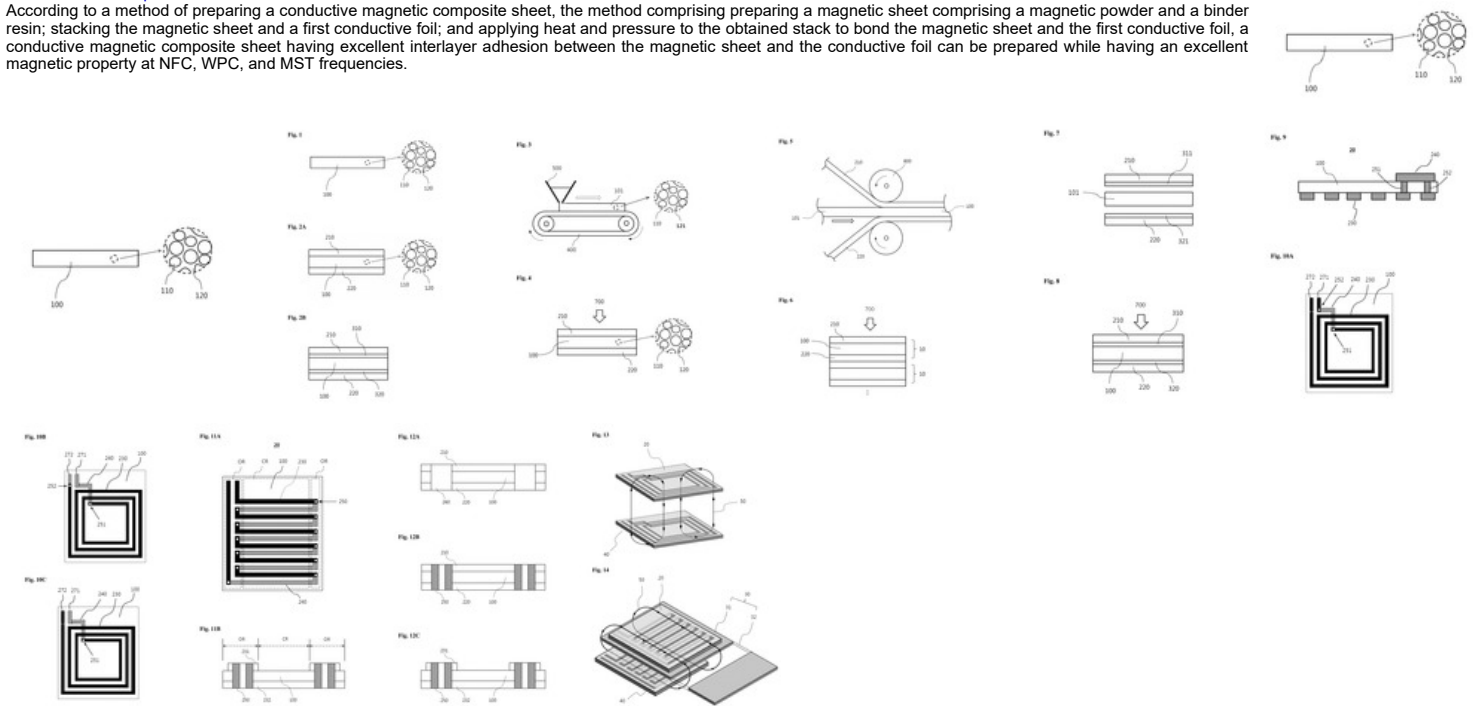
製品区分	対F402	対F406
基準額(100)の相対関係	1.00	1.71
同様に、対F406の相対関係	1.70	1.26
製品の変動	-0.60	-0.55
成長の減少率 (%)	29.9%	31.4%
成長の平均変化	-0.09	
成長の平均減少率 (%)	29.7%	



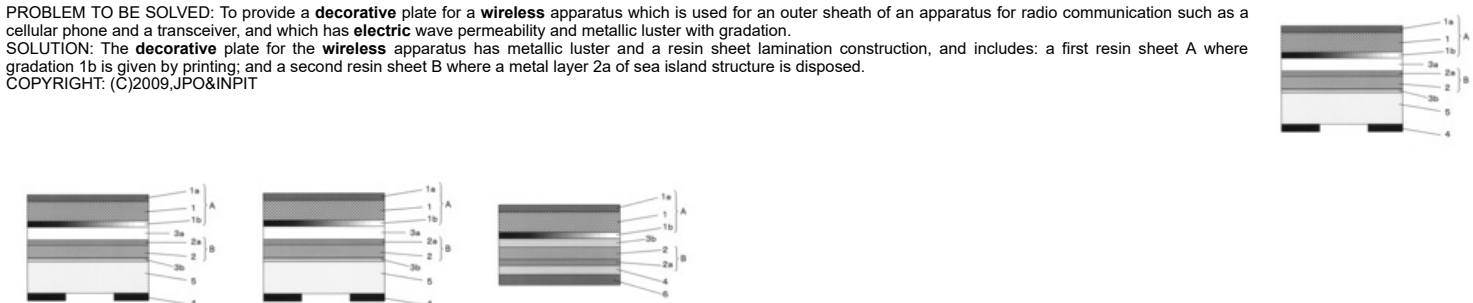
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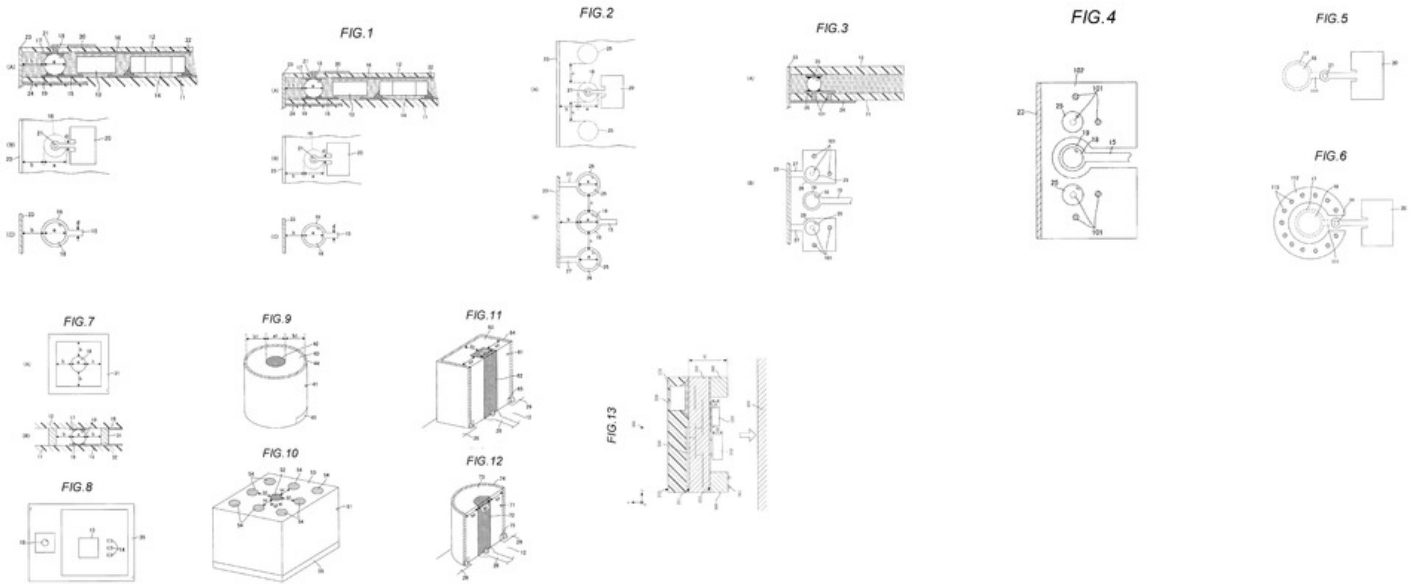
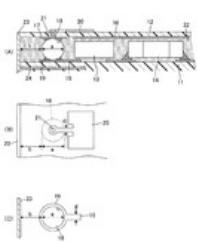
According to a method of preparing a conductive magnetic composite sheet, the method comprising preparing a magnetic sheet comprising a magnetic powder and a binder resin; stacking the magnetic sheet and a first conductive foil; and applying heat and pressure to the obtained stack to bond the magnetic sheet and the first conductive foil, a conductive magnetic composite sheet having excellent interlayer adhesion between the magnetic sheet and the conductive foil can be prepared while having an excellent magnetic property at NFC, WPC, and MST frequencies.



PROBLEM TO BE SOLVED: To provide a **decorative** plate for a **wireless** apparatus which is used for an outer sheath of an apparatus for radio communication such as a cellular phone and a transceiver, and which has **electric** wave permeability and metallic luster with gradation.
SOLUTION: The **decorative** plate for the **wireless** apparatus has metallic luster and a resin sheet lamination construction, and includes: a first resin sheet A where gradation 1b is given by printing; and a second resin sheet B where a metal layer 2a of sea island structure is disposed.
COPYRIGHT: (C)2009,JPO&INPIT

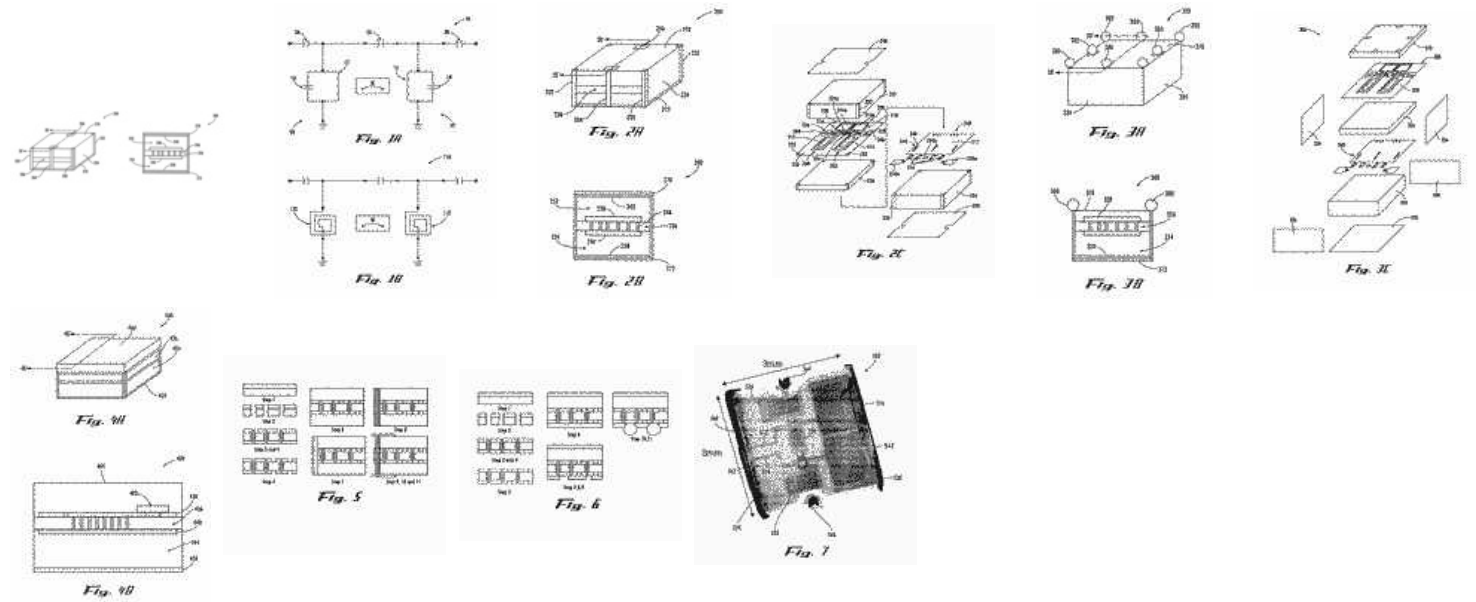


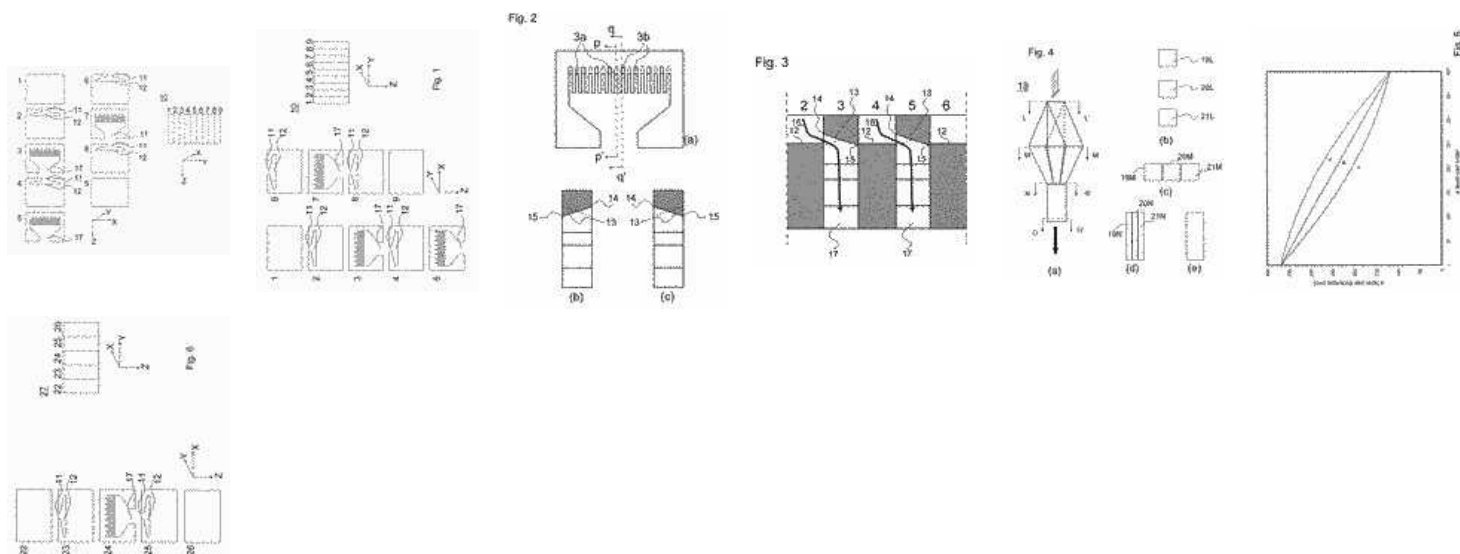
The present invention has a first circuit board (11) on which is mounted the mounting component of a **wireless** circuit, and a second circuit board (12) laminated and disposed in relation to the first circuit board (11); the first circuit board (11) and the second circuit board (12) being **electrically** connected by a connecting member (18) comprising a Cu-core ball and other parts. A conductive member (23) for adjusting impedance is provided laterally to the connecting member (18) in a position a predetermined distance from the connecting member (18), to maintain the signal path of the connecting member (18) at a predetermined impedance.



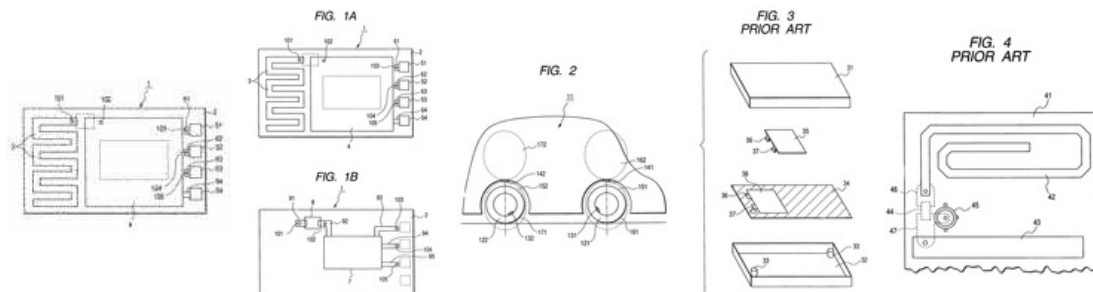
15. **Liquid crystalline polymer- and multilayer polymer-based passive signal processing components for rf/wireless multi-band applications**

The present invention provides all organic fully-packaged miniature bandpass filters, baluns, duplexers, multiplexers, couplers and a combination of the above manufactured using liquid crystalline polymer (LCP) and other multilayer polymer based substrates. These devices are manufactured using one or more LCP layers having integrated passive components formed thereon to provide the density and performance necessary for multi-band **wireless** devices. In the designs involving multiple LCP layers, the LCP layers are separated by prepreg layers. In accordance with an aspect of the present invention, coplanar waveguide, hybrid stripline/coplanar waveguide and/or microstrip topologies are utilized to form the integrated passive components, and the devices can be mass produced on large area panels at least 18 inches by 12 inches with line widths smaller than 10um.

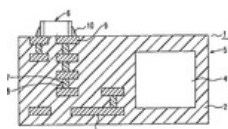




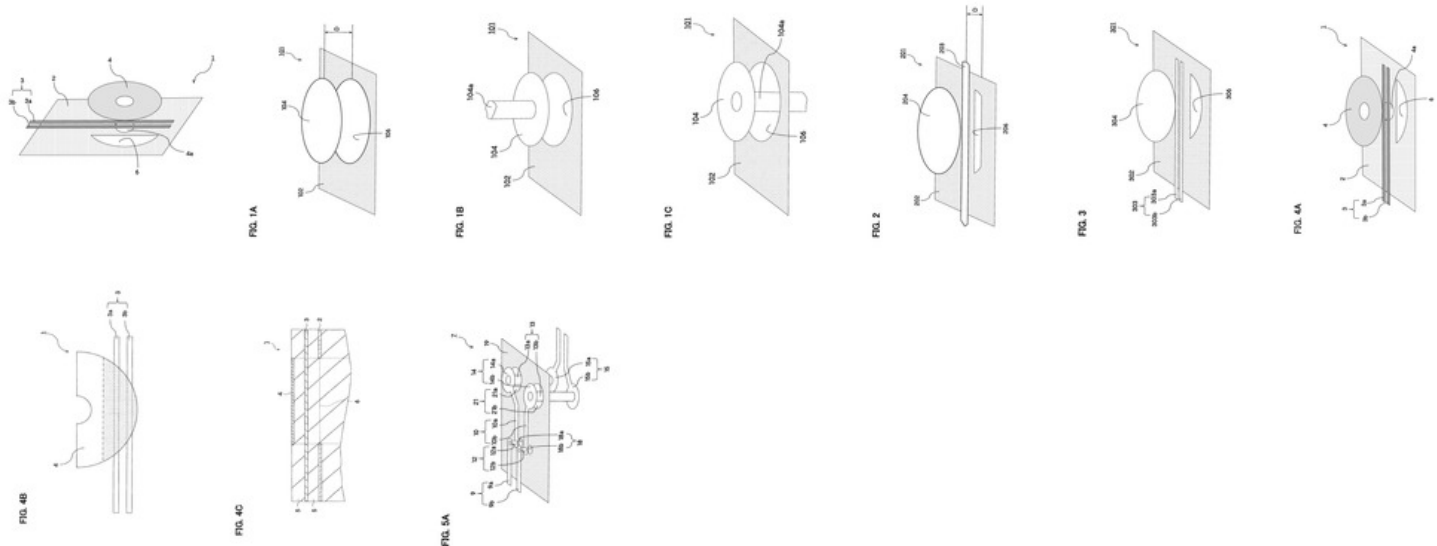
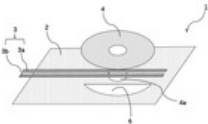
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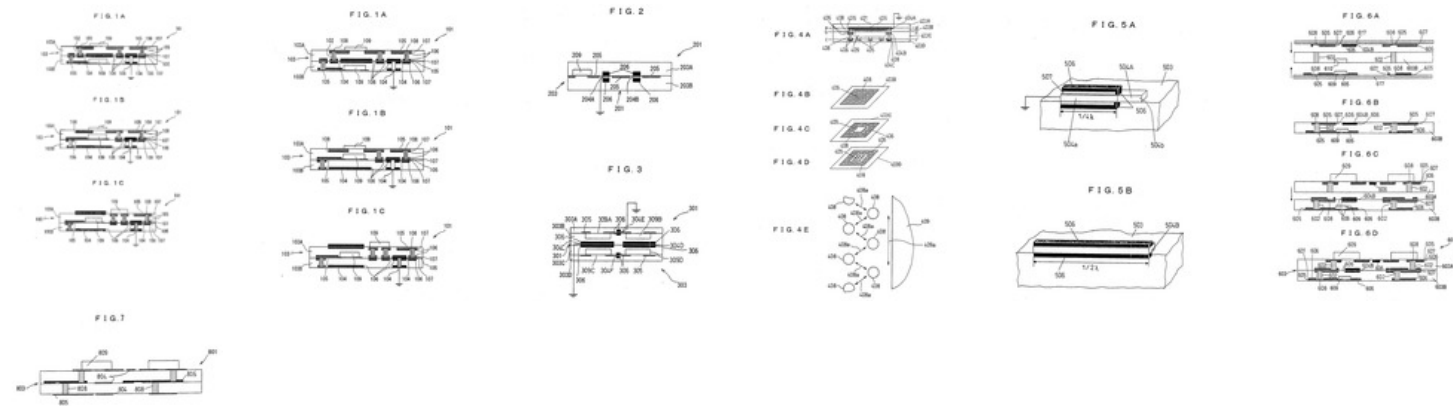
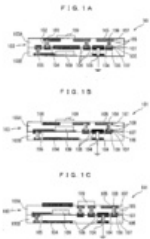
2004-05-13 2004-05-13



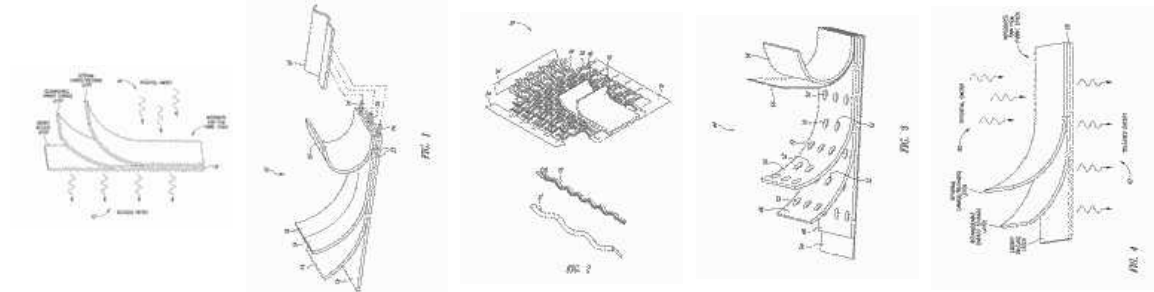
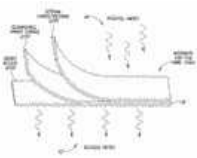
Lamination circuit board in which ground and conductor layers are laminated via an **electrically** insulating layer. Various configurations allow the ground layer to realize characteristic impedance matching in the circuit board: (a) One having at least a removal region where at least a projection region, being the conductor layer orthogonally projected onto the ground layer, is removed; (b) One in which in the lamination the conductor layer, a signal transmission line, and the ground layer are laminated in that order via the **electrically** insulating layer, and having at least a removal region where the conductor layer and the signal transmission line overlap; and (c) One in which in the lamination a signal transmission line, the ground layer, and the conductor layer are laminated in that order via the **electrically** insulating layer, and having at least a removal region where the conductor layer and the signal transmission line overlap.



A signal transmitting lead 105 is provided on an **electrically** insulating layer 103 . Auxiliary leads 104 A and 104 B are provided while the auxiliary leads 104 A and 104 B are not in **electrical** contact with the signal transmitting lead 105 . At least a part of the auxiliary leads 104 A and 104 B is covered with an electromagnetic shielding layer 106 . Consequently, radiant noise from the inside or the outside of a printed wiring board can be suppressed without degrading characteristics of a signal which is transmitted through the signal transmitting lead 105.



A material is provided that includes a first section for storing energy and a second section for releasing energy received from the first section in which the energy is preferably **electrical** energy that is used for one from among heat dissipation, heat generation, light emission and powering of an **electric** circuit. Ideally the material includes a third layer adapted to collect energy and convert the energy to **electrical** energy for storage in the first section. A fourth protection section is provided on at least one side of the material. The material can be formed of woven strips, laminated sections, or in coaxial sections that are woven together to form a flexible fabric material having at least one characteristic from among breathability, wickability, moisture resistance, moisture-proof, and stretchability.



An actively-powered temperature data logger patch with **wireless** data communication includes a sealed, flexible battery comprising a printed electrochemical cell with an anode and a cathode, and a flexible circuit including a microprocessor, a temperature sensor configured to sense a temperature of a target subject, a **wireless** communication transmitter and an antenna. In one example, the temperature sensor is located at a first end of the patch, and the antenna is located at an opposite, second end of the patch. The patch is configured to conform to a curved surface of the target subject and includes an adhesive configured to be removably applied to skin of the patient. An external computing device is capable of receiving communication from the **wireless** communication transmitter of the patch via an electromagnetic field.



FIG. 1

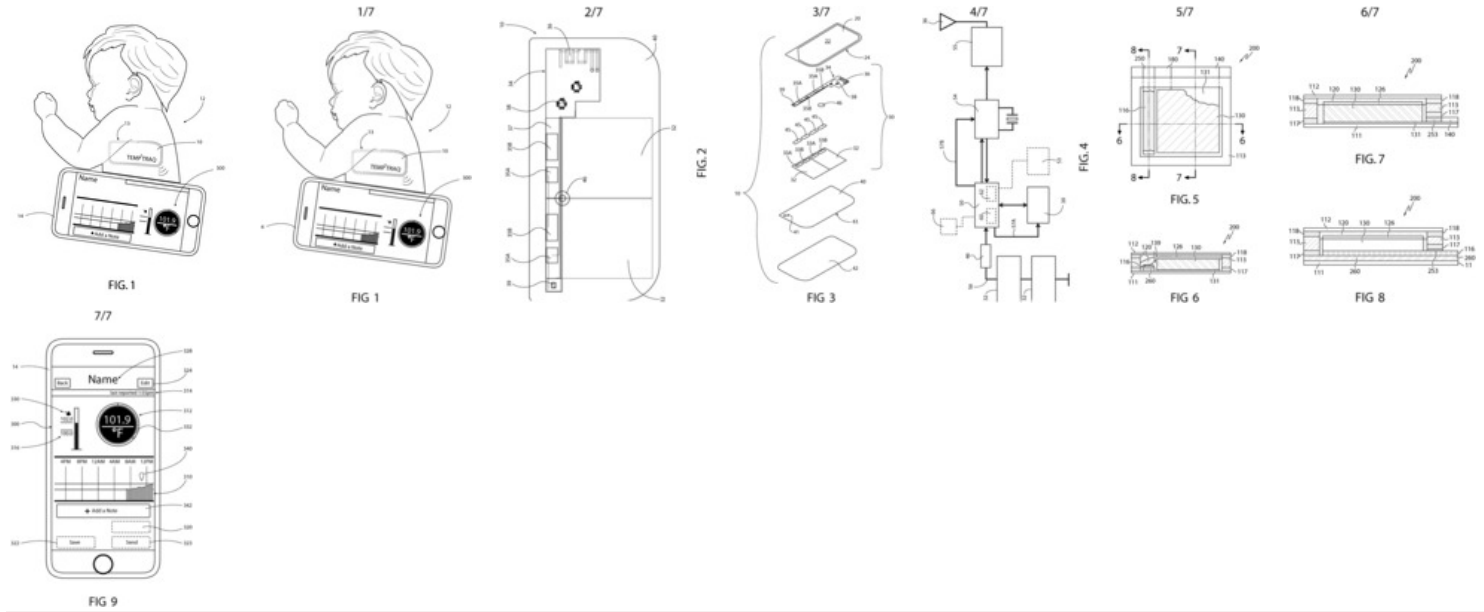
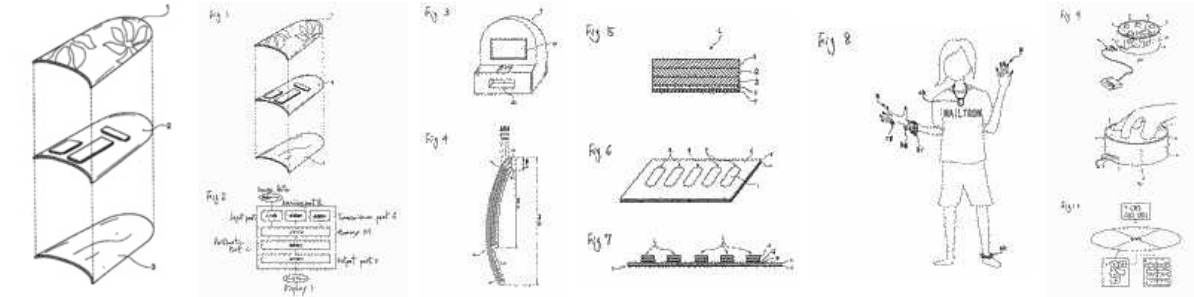
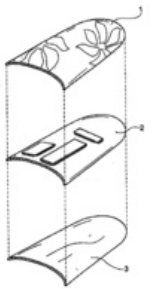


FIG. 9

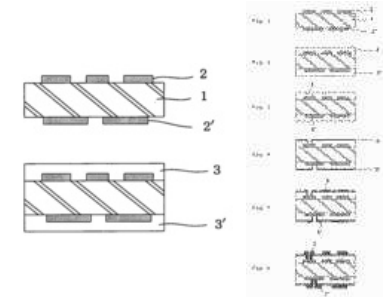
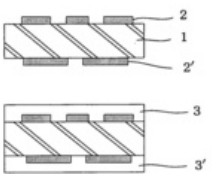
23.	Nail chip mounted with image display device	WO2008053941	2006-11-01	BOOFOOWOO* BOOFOOWOO COM* BUCHUUU LIMITED COMPANY BOOFOOWOO COM	2008-05-08	2008-05-08
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[PROBLEMS] To provide a nail chip that without wasting a paint and remover for use on nail, or container thereof, etc., is self-luminous in the dark so as to vividly illuminate the fingertip there. [MEANS FOR SOLVING PROBLEMS] A **laminated** comprising at least a circuit substrate mounted with a memory for storing of inputted or received image data and with an arithmetic part for arithmetic operation of the image data and outputting of the results; a display device for displaying an image in accordance with the data outputted by the arithmetic part; and a battery for supplying **electric** power to the circuit and the display device, which **laminated** is formed into a nail configuration having the display device as an integumentary layer.



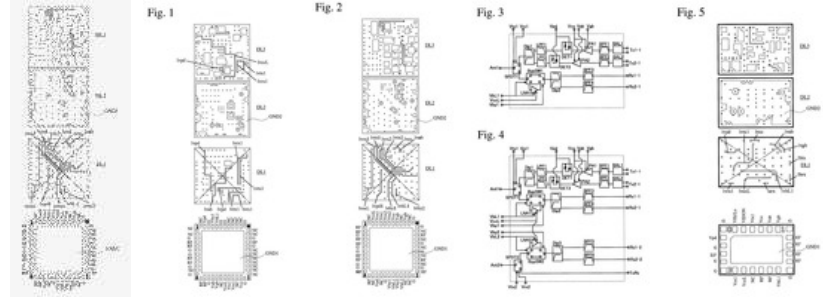
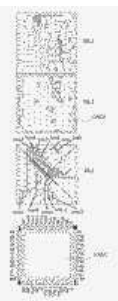
24.	Partial plating method, partially-plated resin base, method for manufacturing multilayer circuit board	WO03072851	2003-02-27	ZEON*	2003-09-04	2003-09-04
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A method for partially plating a resin base to form a patterned plating layer on it. The method comprises the steps of oxidizing a resin base, allowing a compound having a structure coordinatable to a metal atom or a metal ion to adhere to the oxidized surface of the resin base in a **pattern** so as to form an initiator **pattern**, forming a plating layer on the initiator **pattern** by electroless plating, and growing, if necessary, the plating layer to a desired thickness. A partially-plated resin base produced by the method, and a method for manufacturing a multilayer circuit board using the partial plating method are also disclosed.

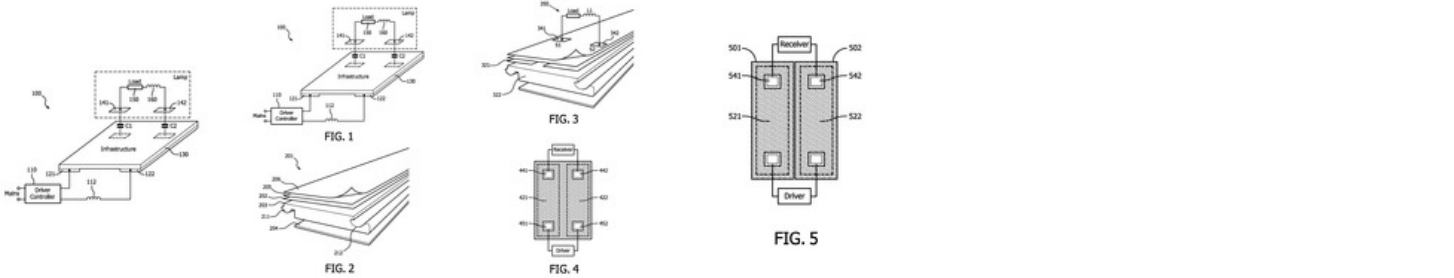


25.	High-frequency part and communication device	WO2008084723	2007-12-27	HITACHI METALS*	2008-07-17	2008-07-17
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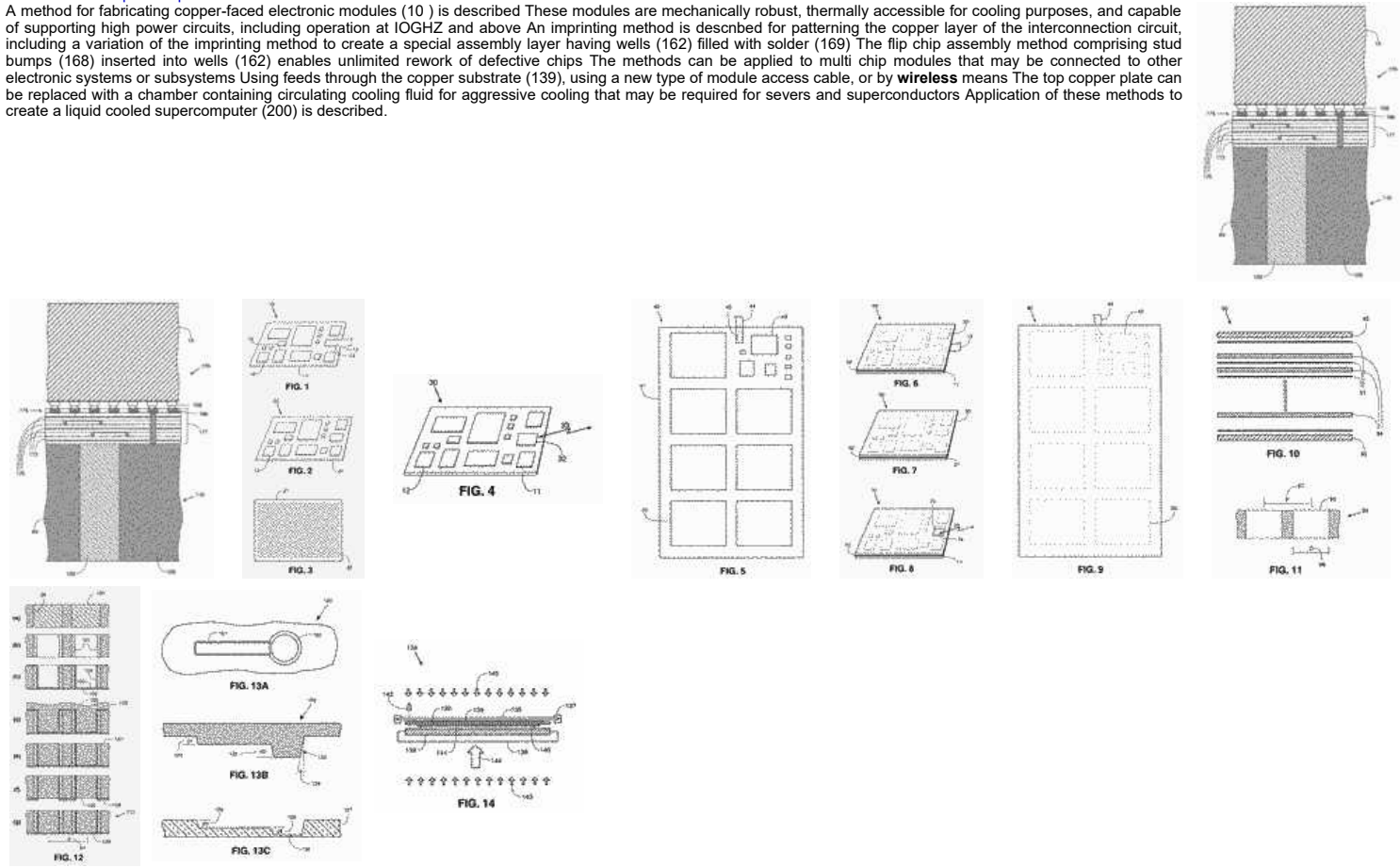
A high-frequency device having high-frequency-signal-treating circuits in and on a **laminated** substrate comprising pluralities of dielectric layers having conductor patterns, the high-frequency-signal-treating circuits having amplifier circuits and switch circuits; terminals including input and output terminals of high-frequency signals, the power supply terminals of the amplifier circuits and the power supply terminals of the switch circuits being formed on one main surface of the **laminated** substrate; power supply lines each having one end connected to each of the power supply terminals of the amplifier circuits and power supply lines each having one end connected to each of the power supply terminals of the switch circuits being formed on one dielectric layer to constitute a power supply line layer; a first ground electrode being arranged on the side of the main surface with respect to the power supply line layer, the first ground electrode overlapping at least part of the power supply lines in a lamination direction; a second ground electrode being arranged on the opposite side of the first ground electrode with respect to the power supply line layer, the second ground electrode overlapping at least part of the power supply lines in a lamination direction; and the high-frequency-signal-treating circuits being arranged on the opposite side of the power supply line layer with respect to the second ground electrode.



A **laminate** panel (201) for **wireless** capacitive power transfer includes a clear protective top layer (206), a photographic layer (205) under the protective top layer (206), a conductive layer (202) under the photographic layer (205), and an inner core layer (203) under the conductive layer (202). One or more conductive layers in the **laminate** panels form a pair of transmitter electrodes, which couple to a power driver (110).



A method for fabricating copper-faced electronic modules (10) is described These modules are mechanically robust, thermally accessible for cooling purposes, and capable of supporting high power circuits, including operation at IOGHZ and above An imprinting method is described for patterning the copper layer of the interconnection circuit, including a variation of the imprinting method to create a special assembly layer having wells (162) filled with solder (169) The flip chip assembly method comprising stud bumps (168) inserted into wells (162) enables unlimited rework of defective chips The methods can be applied to multi chip modules that may be connected to other electronic systems or subsystems Using feeds through the copper substrate (139), using a new type of module access cable, or by **wireless** means The top copper plate can be replaced with a chamber containing circulating cooling fluid for aggressive cooling that may be required for servers and superconductors Application of these methods to create a liquid cooled supercomputer (200) is described.



28.

Biocomposite material and method of making

WO9404360

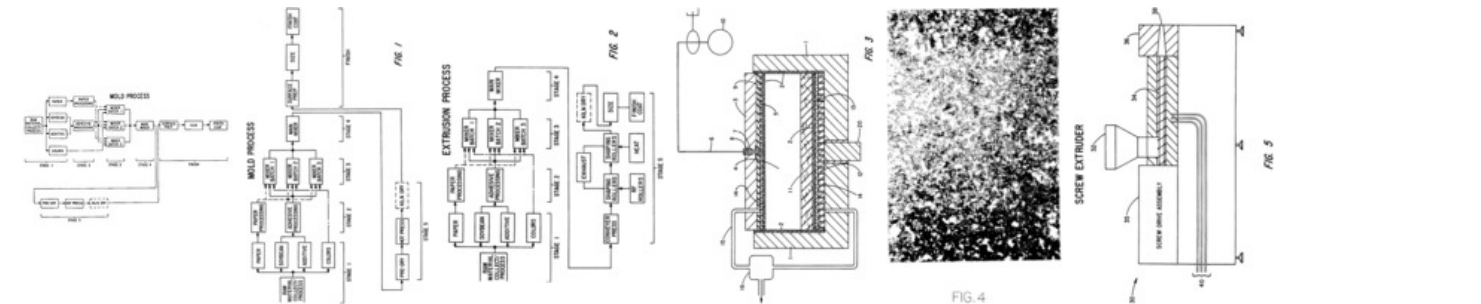
1993-06-16

PHENIX BIOCOSMITES*

1994-03-03

1994-03-03

Fiber-reinforced protein-based biocomposite particulate material containing a legume-based thermosetting resin and cellulosic material, and rigid biocomposite pressure-formed materials produced therefrom, are provided. The particulate material and resultant pressure-formed materials contain the legume-based resin and fibrous cellulosic material in amounts such that the ratio of cellulose solids to resin solids is about 0.8:1.0 to about 1.5:1.0. Particularly preferred pressure-formed materials also include a secondary thermosetting binder, such as an isocyanate.



29.

Dielectric filter

JPH10107503

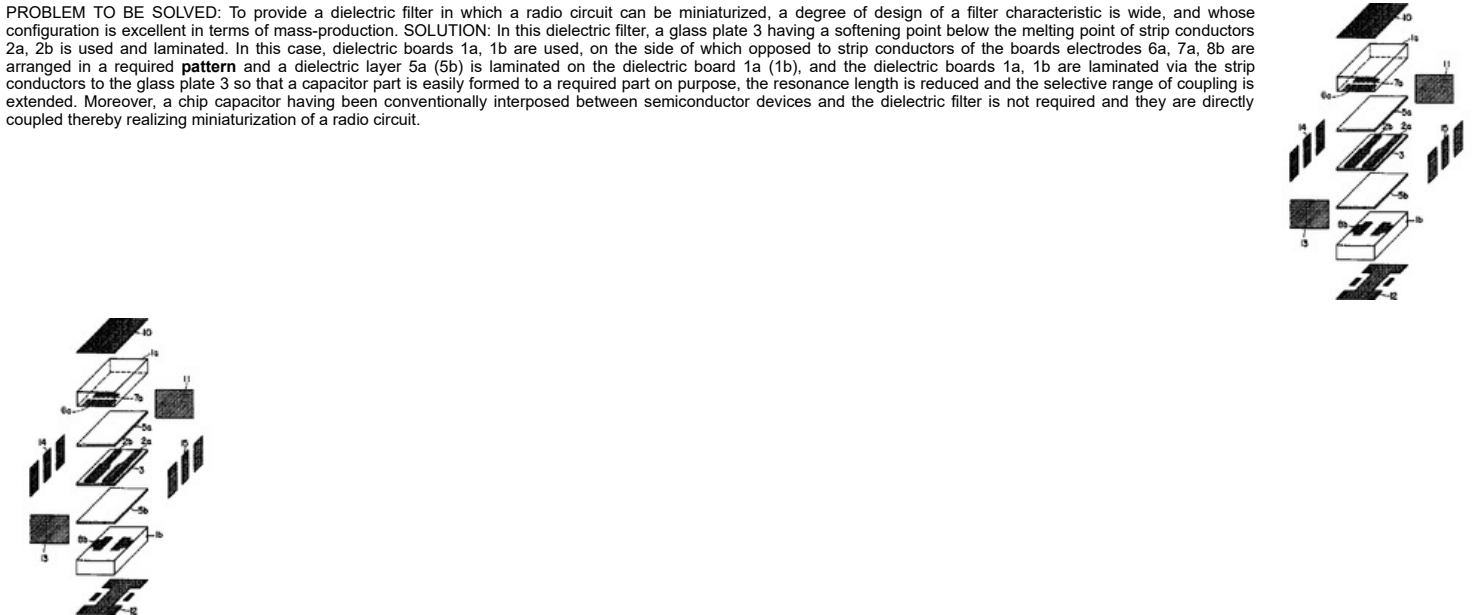
1996-09-27

SUMITOMO SPECIAL METALS*

1998-04-24

1998-04-24

PROBLEM TO BE SOLVED: To provide a dielectric filter in which a radio circuit can be miniaturized, a degree of design of a filter characteristic is wide, and whose configuration is excellent in terms of mass-production. SOLUTION: In this dielectric filter, a glass plate 3 having a softening point below the melting point of strip conductors 2a, 2b is used and laminated. In this case, dielectric boards 1a, 1b are used, on the side of which opposed to strip conductors of the boards electrodes 6a, 7a, 8b are arranged in a required pattern and a dielectric layer 5a (5b) is laminated on the dielectric board 1a (1b), and the dielectric boards 1a, 1b are laminated via the strip conductors to the glass plate 3 so that a capacitor part is easily formed to a required part on purpose, the resonance length is reduced and the selective range of coupling is extended. Moreover, a chip capacitor having been conventionally interposed between semiconductor devices and the dielectric filter is not required and they are directly coupled thereby realizing miniaturization of a radio circuit.



30.

Substrate and method of forming the same

US20150333004

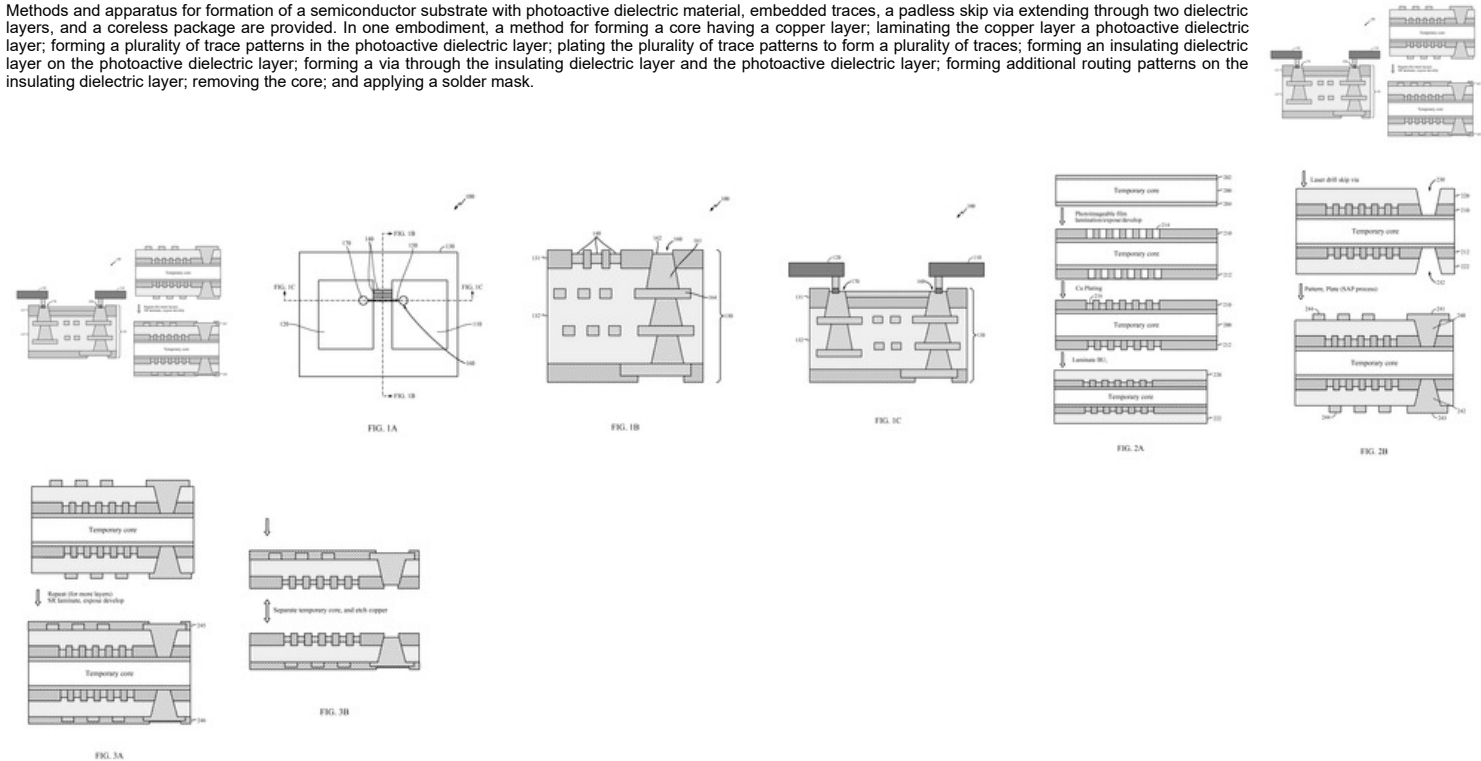
2014-05-13

QUALCOMM*

2015-11-19

2015-11-19

Methods and apparatus for formation of a semiconductor substrate with photoactive dielectric material, embedded traces, a padless skip via extending through two dielectric layers, and a coreless package are provided. In one embodiment, a method for forming a core having a copper layer; laminating the copper layer a photoactive dielectric layer; forming a plurality of trace patterns in the photoactive dielectric layer; plating the plurality of trace patterns to form a plurality of traces; forming an insulating dielectric layer on the photoactive dielectric layer; forming a via through the insulating dielectric layer and the photoactive dielectric layer; forming additional routing patterns on the insulating dielectric layer; removing the core; and applying a solder mask.



A high-frequency circuit device comprising at least first and second antenna terminals, at least first and second transmitting terminals for a first communications system, at least first and second receiving terminals for a first communications system, two or more switch circuits, and two or more filter circuits, the first transmitting terminal for the first communications system being connectable to the first antenna terminal, the second transmitting terminal for the first communications system being connectable to the second antenna terminal, the first receiving terminal for the first communications system being connectable to the first antenna terminal, and the second receiving terminal for the first communications system being connectable to the second antenna terminal.

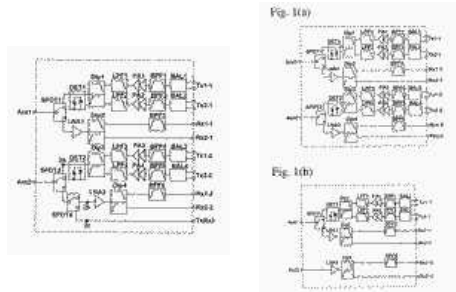
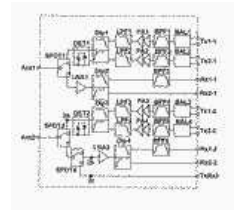


Fig. 2

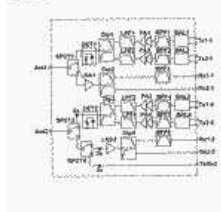


Fig. 3

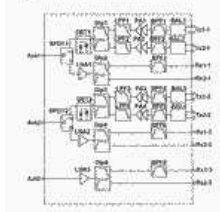


Fig. 4

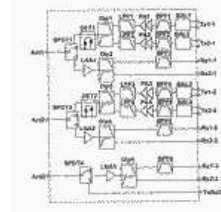


Fig. 5

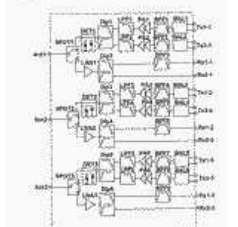


Fig. 6

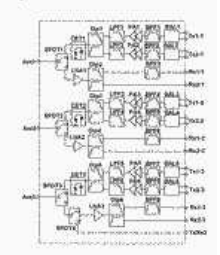


Fig. 7

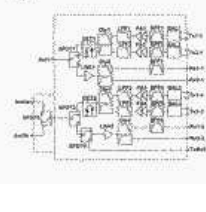


Fig. 8

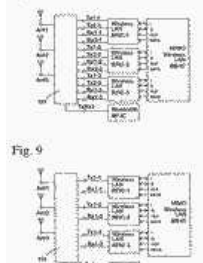
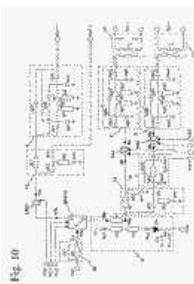
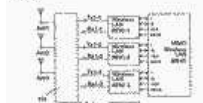


Fig. 9



A hybrid integrated circuit device having high mounting reliability, comprising a modular substrate of ceramic wiring board, a plurality of electronic components built in the principal surface of the modular substrate, a plurality of electrode terminals provided on the rear surface of the modular substrate, and a cap secured to the modular substrate while covering the principal surface of the modular substrate. The electrode terminals include a plurality of electrode terminals arranged along the edge of the modular substrate, and power supply potential supply terminals arranged on the inner side of the plurality of electrode terminals, wherein the electrode terminals arranged along the edge of the modular substrate are covered with a protective film at least the part close to the electrode terminals. The protective film is not thicker than ten and several μm . A connection strength enhancing terminal comprises a plurality of split terminals independent of each other. The connection strength enhancing terminal is a ground terminal.

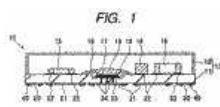
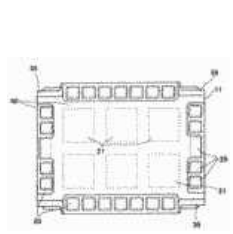
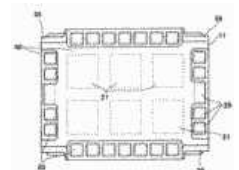


FIG. 2

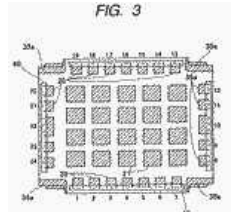


FIG. 3

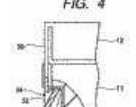
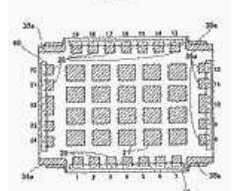


FIG. 4

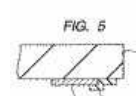


FIG. 5

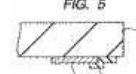


FIG. 6

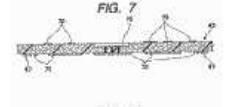


FIG. 7

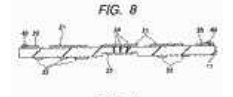


FIG. 8

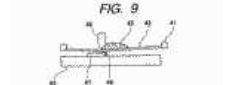


FIG. 9

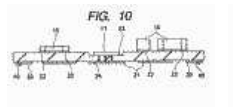


FIG. 10

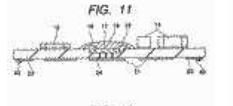
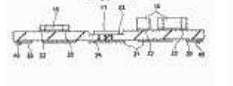


FIG. 11

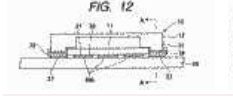
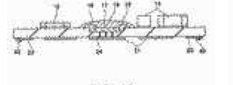


FIG. 12

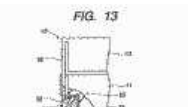
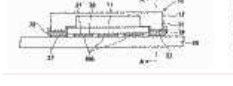


FIG. 13

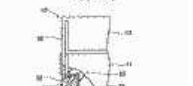


FIG. 14

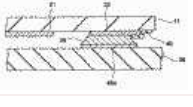


FIG. 15

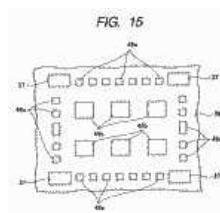
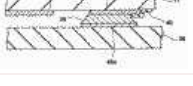


FIG. 16

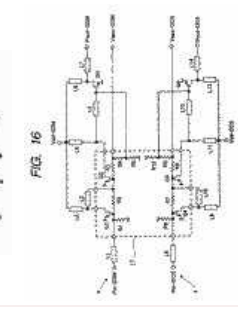
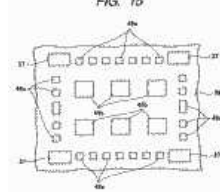
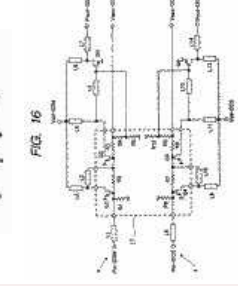
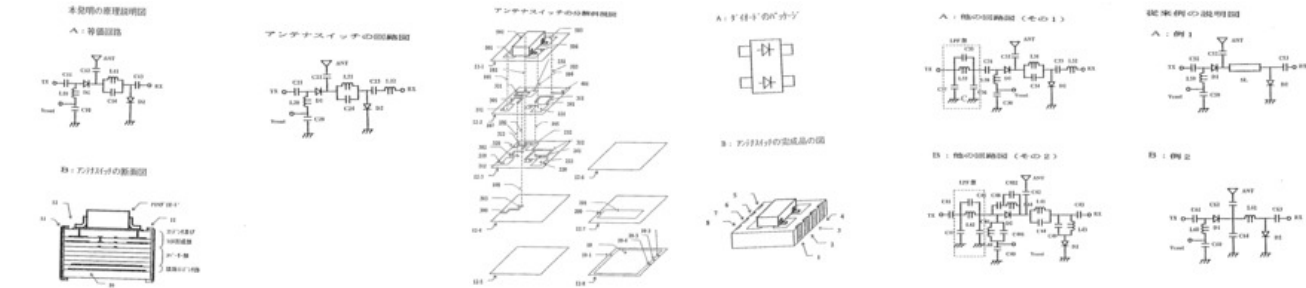
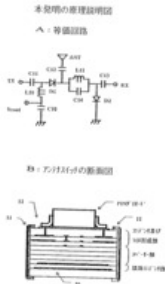


FIG. 17



PROBLEM TO BE SOLVED: To realize a small-sized and thin antenna switch and to reduce the insertion loss to realize sufficient isolation. SOLUTION: In the antenna switch which is provided with a first PIN diode D1 close to a control power terminal Vcont, a second PIN diode D2 following this diode D1, and an inductance element (coil L11) connected between first and second PIN diodes and controls turning-on/off of PIN diodes by the control power of the control power terminal to perform switching between transmission and reception, a capacitive element (capacitor C14) for impedance correction is connected in parallel to the inductance element. A passive element is formed on plural dielectric sheets by patterning, and PIN diodes D1 and D2 are mounted on a multilayered substrate 12 obtained by laminating and forming them, and external connection terminals are provided in side face parts of the multilayered substrate 12.



The invention relates to high-frequency devices including a high-frequency transmission line, high-frequency filter, and resonator, and a main object is to compact the high-frequency device without decreasing "Q" of the device. To achieve the object, the high-frequency device of the present invention is constituted by putting the internal conductor (5) used for resonators and so on between the high dielectric layers (2 and 3) (made of a material with a high dielectric constant), putting the layers (2 and 3) between low dielectric layers (1 and 4) (made of a material with a low dielectric constant), and further putting the layers (1 and 4) between GND electrodes (6 and 7).

